

### Amendments to the Claims

1. (original) A method of manufacturing a ball grid array semiconductor package comprising the steps of:

    providing a substrate, wherein said substrate comprises a first surface and a second surface and said first surface or said second surface comprises a conductor pattern;

    providing a plurality of conductive bump contact areas on said first surface of said substrate;

    substantially aligning each of said conductive bump contact areas with at least one conductive bump, wherein the step of substantially aligning said conductive bump contact areas with at least one of said conductive bumps comprises the step of vibrating at least a portion of said substrate, wherein said vibration of at least a portion of said substrate substantially aligns each of said conductive bump contact areas with at least one of said conductive bumps; and

    disposing at least one of said conductor bumps on each of said conductive bump contact areas.

2. (original) The method of claim 1, wherein the step of vibrating at least a portion of said substrate comprises the step of ultrasonically vibrating at least a portion of said substrate.

3. (original) The method of claim 2, wherein the step of ultrasonically vibrating at least a portion of said substrate comprises the step of ultrasonically vibrating a first end, a second end, and a third end of a film strip on which at least one of said substrates is disposed.

4. (original) The method of claim 2, further comprising the step of discontinuing said ultrasonic vibration of at least a portion of said substrate when each of said

conductive bump contact areas are substantially aligned with at least one of said conductive bumps.

5. (original) The method of claim 4, wherein said conductive bumps comprise solder.

6 - 11 (cancelled).

12. (new) A method of manufacturing a ball grid array semiconductor package comprising the steps of:

providing a substrate, wherein said substrate comprises a first surface and a second surface and said first surface or said second surface comprises a conductor pattern;

providing a plurality of conductive bump contact areas on said first surface of said substrate;

substantially aligning each of said conductive bump contact areas with at least one conductive bump, wherein the step of substantially aligning said conductive bump contact areas with at least one of said conductive bumps comprises the step of vibrating at least a portion of said substrate, wherein said vibration of at least a portion of said substrate substantially aligns each of said conductive bump contact areas with at least one of said conductive bumps;

disposing at least one of said conductor bumps on each of said conductive bump contact areas; and

reflowing said conductor bumps disposed on said conductive bump contact areas.

13. (new) The method of claim 12, wherein the step of vibrating at least a portion of said substrate comprises the step of ultrasonically vibrating at least a portion of said substrate.

14. (new) The method of claim 12, wherein the step of vibrating at least a portion of said substrate comprises the step of vibrating a first end, a second end, and a third end of a film strip on which at least one of said substrates is disposed.
15. (new) The method of claim 12, further comprising the step of discontinuing said vibration of at least a portion of said substrate when each of said conductive bump contact areas are substantially aligned with at least one of said conductive bumps.
16. (new) The method of claim 12, wherein said conductive bumps comprise solder.